

Type	Function	ROM (byte)	RAM (nibble)	I/O Port (bit)	Min. Instruction Execution Time (μs)	Supply Voltage (V)	Package	Piggyback	One-time PROM		
TMP47C200BN/BF	Standard (LED driver)	2K	128	36	1.9	2.7~6.0	SDIP42	TMP47C990E/G	TMP47P400VN/VF		
TMP47C400BN/BF		4K	256	58			QFP44	TMP47C960AE	—		
TMP47C460AN/AF				SDIP64			QFP67	TMP47C991E/G	TMP47P410AN/AF		
TMP47C210AN/AF	VFT driver	2K	128	36	1.9 (244)	4.5~6.0	SDIP42	TMP47C991E/G	TMP47P410AN/AF		
TMP47C410AN/AF		4K	256	35			SDIP42				
TMP47C212AN		2K	128				55	SDIP42	—		
TMP47C412AN		4K	256	SDIP64				TMP47C975AE			
TMP47C475AN	D/A conversion (PWM) output Watchdog timer	4K	256	55	1.9 (244)	SDIP64	TMP47C975AE	—			
TMP47C221AF	LCD driver	2K	192	28	1.9	4.5~6.0	QFP64	TMP47C921AG	TMP47P421AF		
TMP47C421AF		4K	256				27	1.9 (244)	—	TMP47C925AG	—
TMP47C423AF									High-speed event counter		
TMP47C425AF						QFP67	TMP47C925AG				
TMP47C231AN	D/A conversion (PWM) output	4-bit A/D conversion input Remo-con pre-processing circuit	2K	128	24	1.9	SDIP30	TMP47C931AE	—		
TMP47C233AN		3-bit A/D conversion input	2K	128	36		SDIP42	TMP47C933AE			
TMP47C433AN		4K	256	20		1.9	SDIP30	—	—		
TMP47C236AN	LED driver	3-bit A/D conversion input	2K		128			24		4.5~6.0	SDIP30
TMP47C336AN		Display on screen	3K	192							
TMP47C237AN		3-bit A/D conversion input	2K	128							
TMP47C337AN	Bar Display in OSD	3K	192	24	1.9 (244)	SDIP30	TMP47C940AE	TMP47P242VN			
TMP47C242BN	A/D converter	LED driver	2K	128	23	2.2~6.0	SDIP30	TMP47C940AE	TMP47P242VN		
TMP47C440AN/AF							256	34	SDIP42	TMP47C940AE/AG	TMP47P440AN/AF
TMP47C441AN/AF									VFT driver	QFP44	TMP47C941AE/AG
TMP47C446AF	LCD driver			24	1.9 (244)	QFP64	TMP47C946AG	TMP47P446VF			
TMP47C451BN	DTMF generator	4K	768	23	16.7	2.2~6.0	SDIP30	TMP47C952AE	TMP47P451VN		
TMP47C452BN/BF				35	8.3		SDIP42	TMP47C952AE/AG	TMP47P452VN/VF		
TMP47C453AN/AF				23	2.1	QFP44	TMP47C953AE/AG	TMP47P453VN/VF			
TMP47C454AN				23	2.1	SDIP30	—	TMP47P454VN			
TMP47C407AN/AF				35	2.1	SDIP42	—	TMP47P407VN/VF			
TMP47C456AF	LCD driver			35	8.3 (244)	QFP80	TMP47C956AG	—			

Note*: Under development, (): For low-frequency operation (inst. Cycle time), Postfix N: Plastic shrunk DIP (SDIP), F: Plastic flat package (QFP), E: Ceramic shrunk DIP (SDIC), G: Ceramic flat package (QFC), Operating temperature: -30 ~ 70°C